FAIRCHILD SEMICONDUCTOR™

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# MM74HC151
# 8-Channel Digital Multiplexer

## General Description

The MM74HC151 high speed Digital multiplexer utilizes advanced silicon-gate CMOS technology. Along with the high noise immunity and low power dissipation of standard CMOS integrated circuits, it possesses the ability to drive 10 LS-TTL loads. The MM74HC151 selects one of the 8 data sources, depending on the address presented on the A, B, and C inputs. It features both true (Y) and complement (W) outputs. The STROBE input must be at a low logic level to enable this multiplexer. A high logic level at the STROBE forces the W output HIGH and the Y output LOW.

The 74HC logic family is functionally as well as pin-out compatible with the standard 74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to $V_{CC}$ and ground.

## Features

- Typical propagation delay data select to output Y: 26 ns
- Wide operating supply voltage range: 2–6V
- Low input current: 1 μA maximum
- Low quiescent supply current: 80 μA maximum (74HC)
- High output drive current: 4 mA minimum

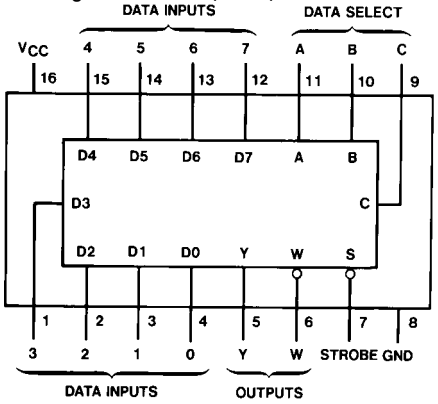
## Ordering Code:

| Order Number | Package Number | Package Description |
|---|---|---|
| MM74HC151M | M16A | 16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow |
| MM74HC151SJ | M16D | 16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide |
| MM74HC151MTC | MTC16 | 16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide |
| MM74HC151N | N16E | 16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide |

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

## Connection Diagram

**Pin Assignments for DIP, SOIC, SOP and TSSOP**




**Top View**

## Truth Table

| Inputs | | | | Outputs | |
|---|---|---|---|---|---|
| Select | | | Strobe | | |
| C | B | A | S | Y | W |
| X | X | X | H | L | H |
| L | L | L | L | D0 | $\overline{D0}$ |
| L | L | H | L | D1 | $\overline{D1}$ |
| L | H | L | L | D2 | $\overline{D2}$ |
| L | H | H | L | D3 | $\overline{D3}$ |
| H | L | L | L | D4 | $\overline{D4}$ |
| H | L | H | L | D5 | $\overline{D5}$ |
| H | H | L | L | D6 | $\overline{D6}$ |
| H | H | H | L | D7 | $\overline{D7}$ |

H = HIGH Level, L = LOW Level, X = Don't Care
D0, D1...D7 = the level of the respective D input

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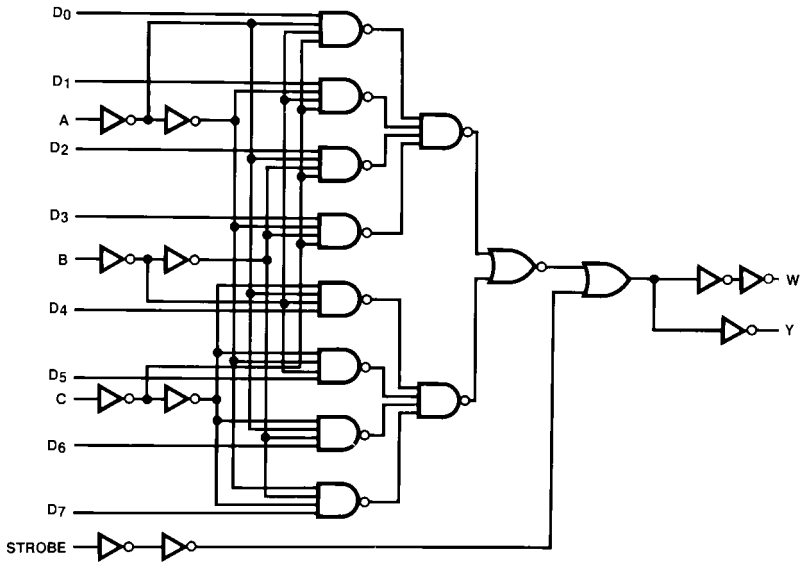
## Logic Diagram



## Absolute Maximum Ratings (Note 1)

(Note 2)

| | |
|---|---|
| Supply Voltage ($V_{CC}$) | −0.5 to +7.0V |
| DC Input Voltage ($V_{IN}$) | −1.5 to $V_{CC}$ +1.5V |
| DC Output Voltage ($V_{OUT}$) | −0.5 to $V_{CC}$ +0.5V |
| Clamp Diode Current ($I_{IK}$, $I_{OK}$) | ±20 mA |
| DC Output Current, per pin ($I_{OUT}$) | ±25 mA |
| DC $V_{CC}$ or GND Current, per pin ($I_{CC}$) | ±50 mA |
| Storage Temperature Range ($T_{STG}$) | −65°C to +150°C |
| Power Dissipation ($P_D$) | |
| (Note 3) | 600 mW |
| S.O. Package only | 500 mW |
| Lead Temperature ($T_L$) | 260°C |
| (Soldering 10 seconds) | |

## Recommended Operating Conditions

| | Min | Max | Units |
|---|---|---|---|
| Supply Voltage ($V_{CC}$) | 2 | 6 | V |
| DC Input or Output Voltage ($V_{IN}$, $V_{OUT}$) | 0 | $V_{CC}$ | V |
| Operating Temperature Range ($T_A$) | −40 | +85 | °C |
| Input Rise or Fall Times | | | |
| ($t_r$, $t_f$) $V_{CC}$ = 2.0V | | 1000 | ns |
| $V_{CC}$ = 4.5V | | 500 | ns |
| $V_{CC}$ = 6.0V | | 400 | ns |

**Note 1:** Absolute Maximum Ratings are those values beyond which damage to the device may occur.

**Note 2:** Unless otherwise specified all voltages are referenced to ground.

**Note 3:** Power Dissipation temperature derating — plastic "N" package: −12 mW/°C from 65°C to 85°C.

## DC Electrical Characteristics (Note 4)

| Symbol | Parameter | Conditions | $V_{CC}$ | $T_A$ = 25°C | $T_A$ = −40 to 85°C | $T_A$ = −55 to 125°C | Units |
|---|---|---|---|---|---|---|---|
| | | | | Typ | Guaranteed Limits | | |
| $V_{IH}$ | Minimum HIGH Level Input Voltage | | 2.0V | | 1.5 | 1.5 | 1.5 | V |
| | | | 4.5V | | 3.15 | 3.15 | 3.15 | V |
| | | | 6.0V | | 4.2 | 4.2 | 4.2 | V |
| $V_{IL}$ | Maximum LOW Level Input Voltage | | 2.0V | | 0.5 | 0.5 | 0.5 | V |
| | | | 4.5V | | 1.35 | 1.35 | 1.35 | V |
| | | | 6.0V | | 1.8 | 1.8 | 1.8 | V |
| $V_{OH}$ | Minimum HIGH Level Output Voltage | $V_{IN}$ = $V_{IH}$ or $V_{IL}$ | | | | | | |
| | | $\|I_{OUT}\| \leq$ 20 μA | 2.0V | 2.0 | 1.9 | 1.9 | 1.9 | V |
| | | | 4.5V | 4.5 | 4.4 | 4.4 | 4.4 | V |
| | | | 6.0V | 6.0 | 5.9 | 5.9 | 5.9 | V |
| | | $V_{IN}$ = $V_{IH}$ or $V_{IL}$ | | | | | | |
| | | $\|I_{OUT}\| \leq$ 4.0 mA | 4.5V | 4.2 | 3.98 | 3.84 | 3.7 | V |
| | | $\|I_{OUT}\| \leq$ 5.2 mA | 6.0V | 5.7 | 5.48 | 5.34 | 5.2 | V |
| $V_{OL}$ | Maximum LOW Level Output Voltage | $V_{IN}$ = $V_{IH}$ or $V_{IL}$ | | | | | | |
| | | $\|I_{OUT}\| \leq$ 20 μA | 2.0V | 0 | 0.1 | 0.1 | 0.1 | V |
| | | | 4.5V | 0 | 0.1 | 0.1 | 0.1 | V |
| | | | 6.0V | 0 | 0.1 | 0.1 | 0.1 | V |
| | | $V_{IN}$ = $V_{IH}$ or $V_{IL}$ | | | | | | |
| | | $\|I_{OUT}\| \leq$ 4.0 mA | 4.5V | 0.2 | 0.26 | 0.33 | 0.4 | V |
| | | $\|I_{OUT}\| \leq$ 5.2 mA | 6.0V | 0.2 | 0.26 | 0.33 | 0.4 | V |
| $I_{IN}$ | Maximum Input Current | $V_{IN}$ = $V_{CC}$ or GND | 6.0V | | ±0.1 | ±1.0 | ±1.0 | μA |
| $I_{CC}$ | Maximum Quiescent Supply Current | $V_{IN}$ = $V_{CC}$ or GND | 6.0V | | 8.0 | 80 | 160 | μA |
| | | $I_{OUT}$ = 0 μA | | | | | | |

**Note 4:** For a power supply of 5V ±10% the worst case output voltages ($V_{OH}$, and $V_{OL}$) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case $V_{IH}$ and $V_{IL}$ occur at $V_{CC}$ = 5.5V and 4.5V respectively. (The $V_{IH}$ value at 5.5V is 3.85V.) The worst case leakage current ($I_{IN}$, $I_{CC}$, and $I_{OZ}$) occur for CMOS at the higher voltage and so the 6.0V values should be used.

## AC Electrical Characteristics

$V_{CC}$ = 5V, $T_A$ = 25°C, $C_L$ = 15 pF, $t_r = t_f$ = 6 ns

| Symbol | Parameter | Conditions | Typ | Guaranteed Limit | Units |
|---|---|---|---|---|---|
| $t_{PHL}$, $t_{PLH}$ | Maximum Propagation Delay A, B or C to Y | | 26 | 35 | ns |
| $t_{PHL}$, $t_{PLH}$ | Maximum Propagation Delay A, B or C to W | | 27 | 35 | ns |
| $t_{PHL}$, $t_{PLH}$ | Maximum Propagation Delay Any D to Y | | 22 | 29 | ns |
| $t_{PHL}$, $t_{PLH}$ | Maximum Propagation Delay any D to W | | 24 | 32 | ns |
| $t_{PHL}$, $t_{PLH}$ | Maximum Propagation Delay Strobe to Y | | 17 | 23 | ns |
| $t_{PHL}$, $t_{PLH}$ | Maximum Propagation Delay Strobe to W | | 16 | 21 | ns |

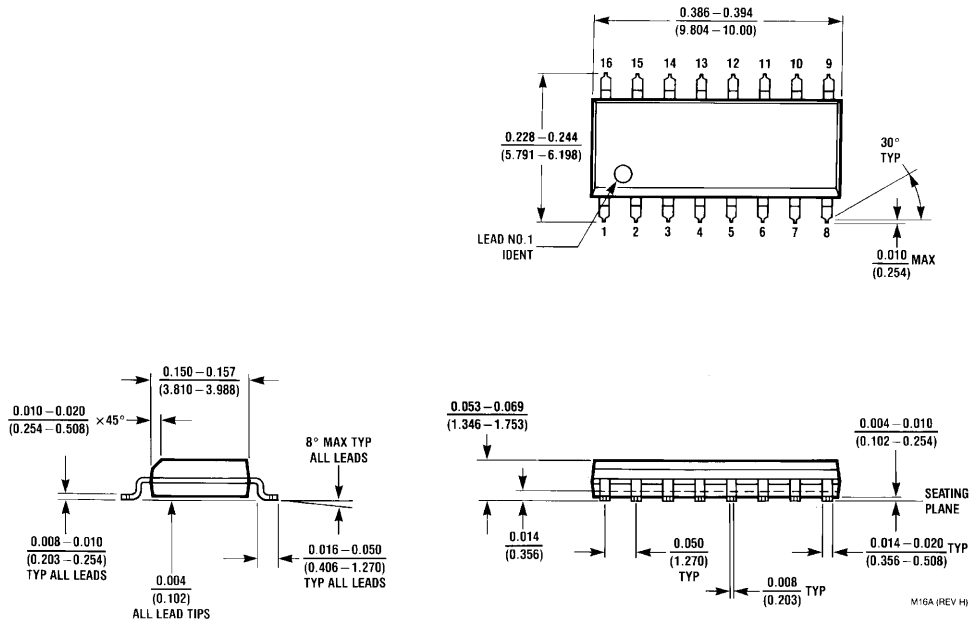
## AC Electrical Characteristics

$C_L$ = 50 pF, $t_r = t_f$ = 6 ns (unless otherwise specified)

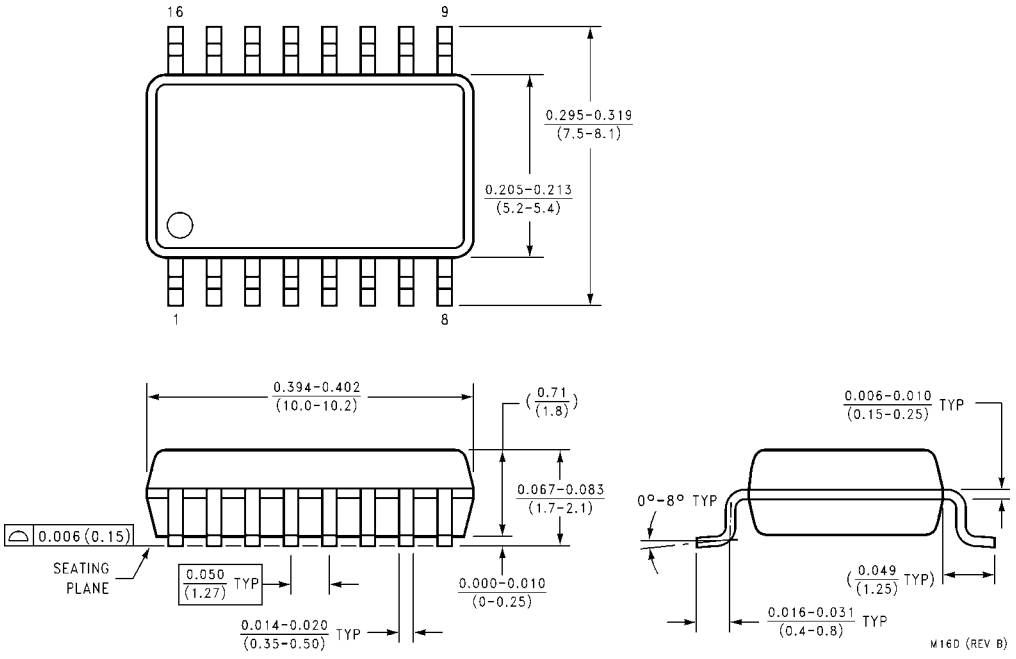
| Symbol | Parameter | Conditions | $V_{CC}$ | $T_A$ = 25°C | $T_A$ = −40 to 85°C | $T_A$ = −55 to 125°C | | Units |
|---|---|---|---|---|---|---|---|---|
| | | | | Typ | Guaranteed Limits | | | |
| $t_{PHL}$, $t_{PLH}$ | Maximum Propagation Delay A, B or C to Y | | 2.0V | 90 | 205 | 256 | 300 | ns |
| | | | 4.5V | 31 | 41 | 51 | 60 | ns |
| | | | 6.0V | 26 | 35 | 44 | 51 | ns |
| $t_{PHL}$, $t_{PLH}$ | Maximum Propagation Delay A, B or C to W | | 2.0V | 95 | 205 | 256 | 300 | ns |
| | | | 4.5V | 32 | 41 | 51 | 60 | ns |
| | | | 6.0V | 27 | 35 | 44 | 51 | ns |
| $t_{PHL}$, $t_{PLH}$ | Maximum Propagation Delay any D to Y | | 2.0V | 70 | 195 | 244 | 283 | ns |
| | | | 4.5V | 27 | 39 | 49 | 57 | ns |
| | | | 6.0V | 23 | 33 | 41 | 48 | ns |
| $t_{PHL}$, $t_{PLH}$ | Maximum Propagation Delay any D to W | | 2.0V | 75 | 185 | 231 | 268 | ns |
| | | | 4.5V | 29 | 37 | 46 | 54 | ns |
| | | | 6.0V | 25 | 32 | 40 | 46 | ns |
| $t_{PHL}$, $t_{PLH}$ | Maximum Propagation Delay Strobe to Y | | 2.0V | 50 | 140 | 175 | 203 | ns |
| | | | 4.5V | 21 | 28 | 35 | 41 | ns |
| | | | 6.0V | 18 | 24 | 30 | 35 | ns |
| $t_{PHL}$, $t_{PLH}$ | Maximum Propagation Delay Strobe to W | | 2.0V | 45 | 127 | 159 | 185 | ns |
| | | | 4.5V | 20 | 25 | 32 | 37 | ns |
| | | | 6.0V | 17 | 22 | 28 | 32 | ns |
| $t_{TLH}$, $t_{THL}$ | Maximum Output Rise and Fall Time | | 2.0V | 30 | 75 | 95 | 110 | ns |
| | | | 4.5V | 8 | 15 | 19 | 22 | ns |
| | | | 6.0V | 7 | 13 | 16 | 19 | ns |
| $C_{PD}$ | Power Dissipation Capacitance (Note 5) | (per package) | | 110 | | | | pF |
| $C_{IN}$ | Maximum Input Capacitance | | | 5 | 10 | 10 | 10 | pF |

**Note 5:** $C_{PD}$ determines the no load dynamic power consumption, $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$, and the no load dynamic current consumption, $I_S = C_{PD} V_{CC} f + I_{CC}$.

## Physical Dimensions inches (millimeters) unless otherwise noted

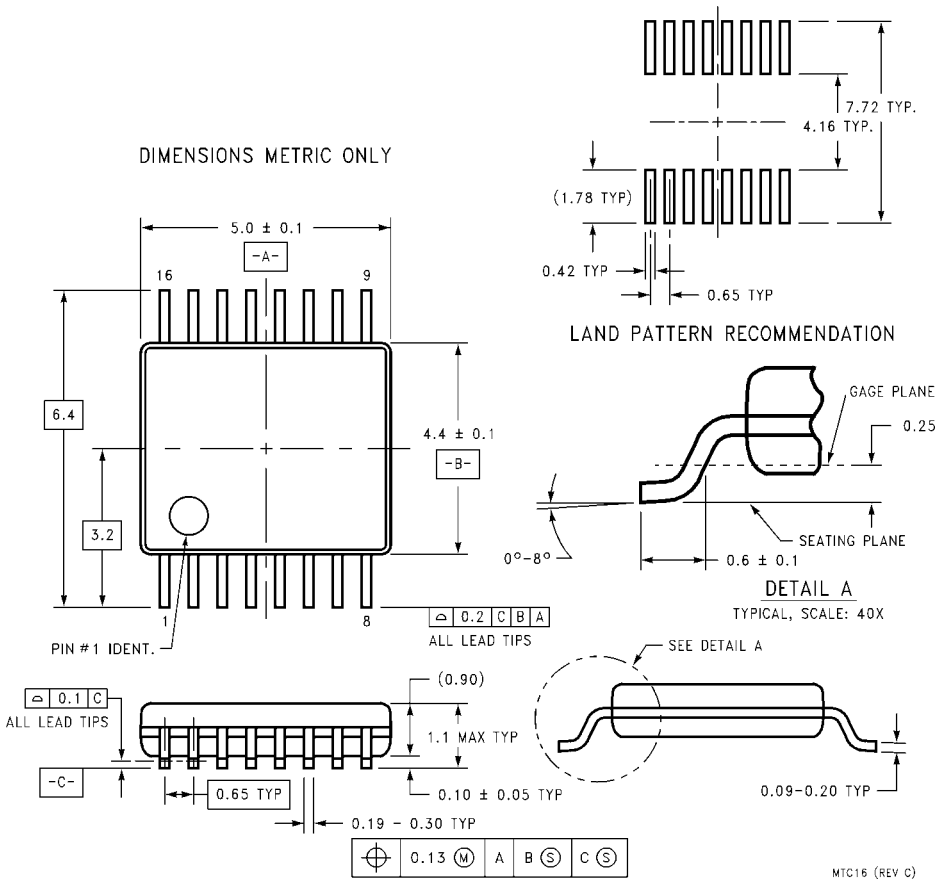



**16-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow**
**Package Number M16A**



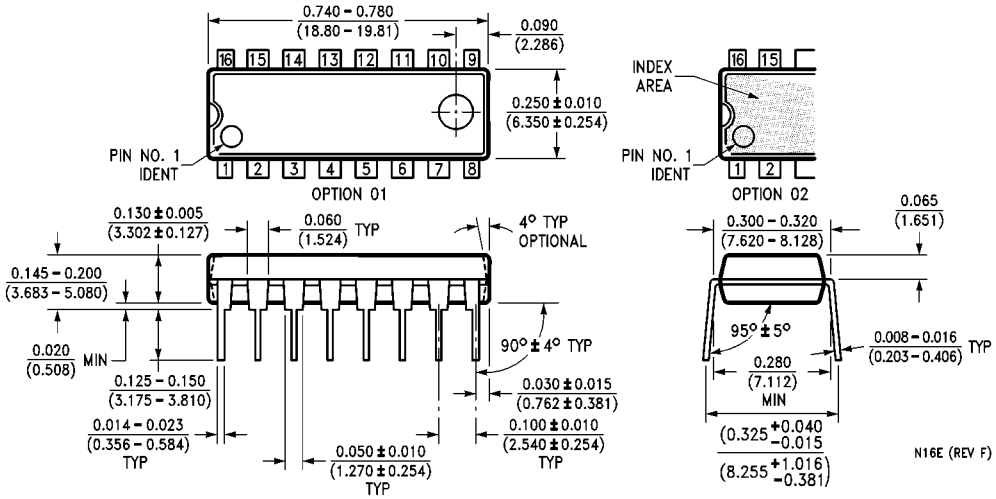

**16-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide**
**Package Number M16D**

## Physical Dimensions inches (millimeters) unless otherwise noted (Continued)




**16-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide**
**Package Number MTC16**

## Physical Dimensions inches (millimeters) unless otherwise noted (Continued)




**16-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide**
**Package Number N16E**

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